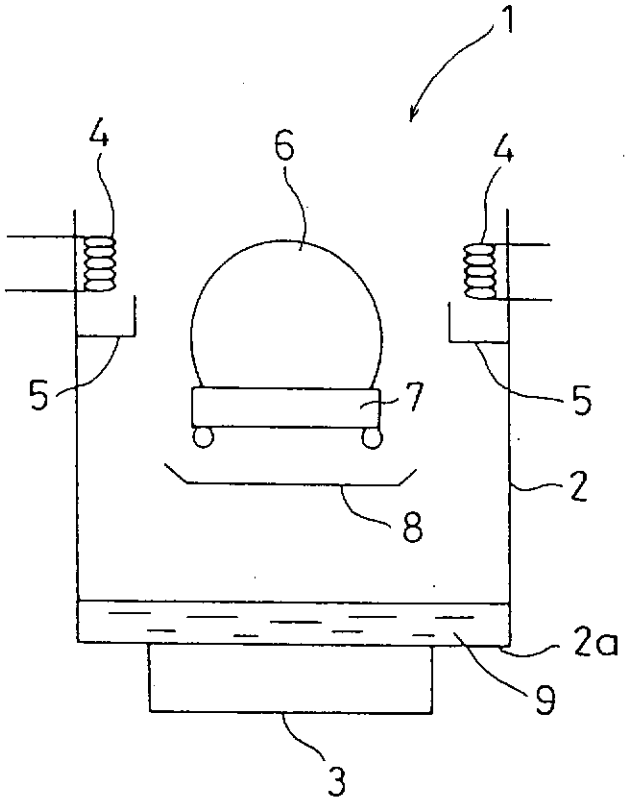


FIG.1

→ PRIOR ART

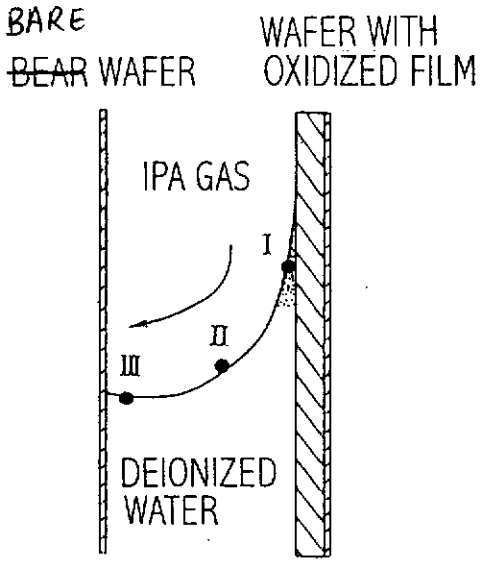

BARE
~~BEAR~~ WAFER
WAFER WITH
OXIDIZED FILM
IPA GAS
I
II
III
DEIONIZED
WATER

FIG.6

INCREASING AMOUNT OF PARTICLES(number/waf.)
NOT LESS THAN 0.13 μm
1450
950
450
-50
MARANGONI DRYING
DRYING METHOD
OF THE INVENTION
WAFER FACING TOWARD WAFER
WITH OXIDIZED FILM(WAFER A)
WAFER FACING TOWARD ~~BEAR~~ Bare WAFER(WAFER B)

FIG.8

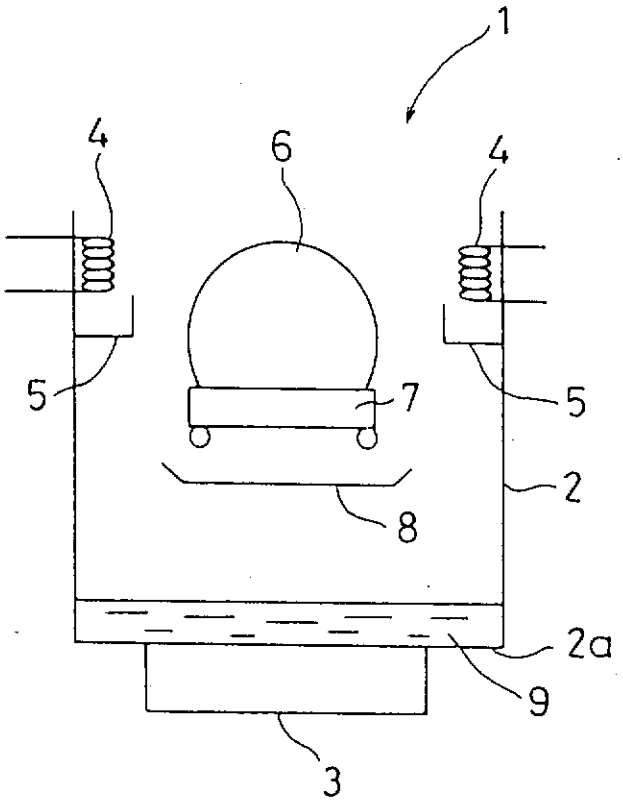


FIG.1

PRIOR ART

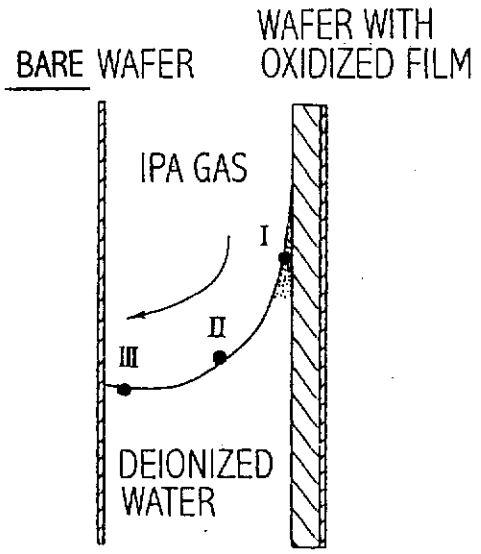

BARE WAFER
WAFER WITH OXIDIZED FILM
IPA GAS
I
II
III
DEIONIZED WATER

FIG.6

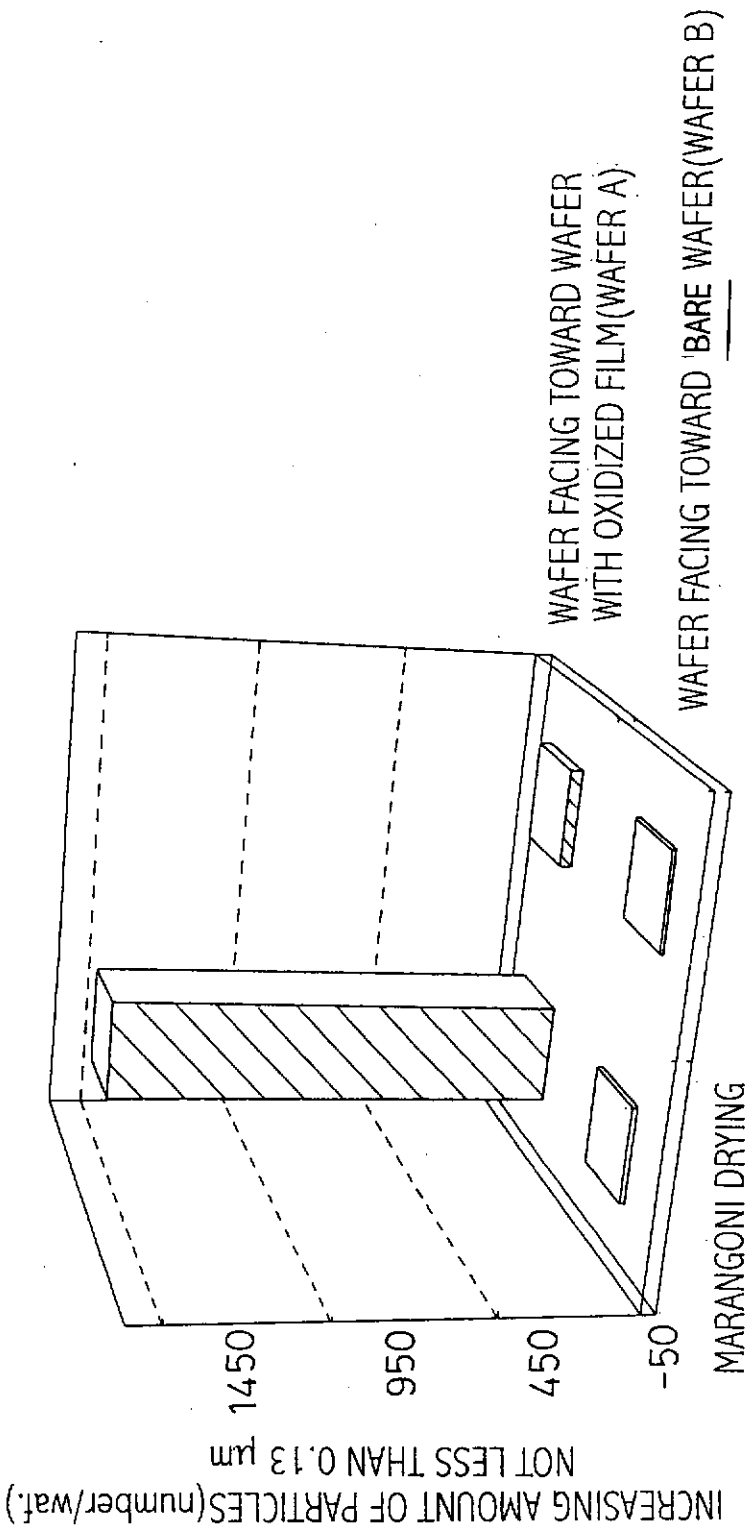

INCREASING AMOUNT OF PARTICLES(number/wat.)
NOT LESS THAN 0.13 μm
1450
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450
-50
MARANGONI DRYING
DRYING METHOD OF THE INVENTION
WAFER FACING TOWARD WAFER WITH OXIDIZED FILM(WAFER A)
WAFER FACING TOWARD BARE WAFER(WAFER B)

FIG.8